Title (en)

Assembly with at least one semiconductor module and a transport package

Title (de)

Anordnung mit mindestens einem Leistungshalbleitermodul und mit einer Transportverpackung

Title (fr)

Agencement doté d'au moins un module semi-conducteur de puissance et d'un emballage de transport

Publication

**EP 2347970 B1 20130619 (DE)**

Application

**EP 10192500 A 20101125**

Priority

DE 102010005047 A 20100120

Abstract (en)

[origin: EP2347970A1] The arrangement (1) comprises a transportation packaging (2) provided with a planar sheet (10), a covering film (30), and a drip-tray type plastic structure (80). The plastic structure partly encloses the power semiconductor module (5). The side of power semiconductor module directly or indirectly rests on the major surface of the planar sheet. The farthest sides of power semiconductor module are covered by the covering film.

IPC 8 full level

**B65D 75/32** (2006.01); **B65D 75/36** (2006.01)

CPC (source: EP KR US)

**B65D 75/327** (2013.01 - EP KR US); **B65D 75/367** (2013.01 - EP KR US); **B65D 81/02** (2013.01 - KR); **B65D 85/30** (2013.01 - KR); B65D 2575/3245 (2013.01 - KR); B65D 2585/86 (2013.01 - EP KR US)

Cited by

US11769701B2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 2347970 A1 20110727**; **EP 2347970 B1 20130619**; CN 102145794 A 20110810; CN 102145794 B 20150401; DE 102010005047 A1 20110721; DE 102010005047 B4 20141023; JP 2011173654 A 20110908; JP 5732261 B2 20150610; KR 20110085871 A 20110727; US 2011180918 A1 20110728; US 8247892 B2 20120821

DOCDB simple family (application)

**EP 10192500 A 20101125**; CN 201110025010 A 20110120; DE 102010005047 A 20100120; JP 2011005746 A 20110114; KR 20100137810 A 20101229; US 201113010621 A 20110120